



THE WORLD'S FIRST SILICON CARBIDE POLISHER THE 6EZ



SiC is a hard material to process. Revasum understands the challenges of working with SiC and has applied our knowledge of SiC grinding, prime silicon substrate polishing and CMP, to develop a unique solution that truly makes polishing SiC easy.

The 6EZ can polish and clean both faces of 50 SiC substrates sequentially, without any operator intervention. Combining the 6EZ with Revasum's fully-automated 7AF-HMG grinder, the entire process flow from wire slicing or laser splitting to EPI is synchronized to provide optimum performance and high yields at an affordable cost per wafer – delivering a production-ready solution for 150mm and 200mm SiC substrate manufacturing.



REQUEST A BROCHURE

POLISH MODULE
WITH DEDICATED HARDWARE

INTEGRATED
CLEANING

MINIMAL
OPERATOR INTERVENTION



Polish Module

The 6EZ polish section consists of an integrated post-polish cleaning module, spindle, carrier, pad conditioner and high-pressure spray system. It provides the best possible wafer-to-wafer cleaning and is configured with up to three slurries (optional).



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